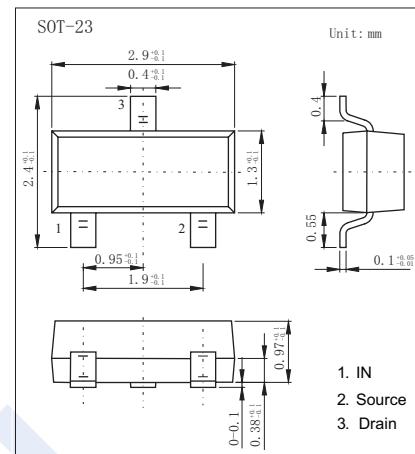


N-Channel Self Protected Enhancement Mode MOSFET ZXMS6004FF(KXMS6004FF)

■ Features

- Compact high power dissipation package
- Low input current
- Logic Level Input (3.3V and 5V)
- Short circuit protection with auto restart
- Over voltage protection (active clamp)
- Thermal shutdown with auto restart
- Over-current protection
- Input Protection (ESD)
- High continuous current rating



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	60	V
Drain-Source voltage for short circuit protection	V _{DS(SC)}	36	
Continuous input Voltage	V _{IN}	-0.5 ... +6	
Continuous input Current -0.2V ≤ V _{IN} ≤ 6V V _{IN} < -0.2V or V _{IN} > 6V	I _{IN}	No limit I _{IN} ≤ 2	mA
Pulsed Drain Current @ V _{IN} = 3.3V	I _{DM}	2	A
Pulsed Drain Current @ V _{IN} = 5V		2.5	
Power Dissipation at TA = 25°C ^(a)	P _D	0.83	W
Linear derating factor		6.66	mW/°C
Power Dissipation at TA = 25°C ^(b)	P _D	1.5	W
Linear derating factor		12	mW/°C
Continuous source current (Body Diode) ^(a)	I _S	1	A
Pulsed dource current (Body Diode)	I _{SM}	5	
Unclamped single pulse inductive energy, T _j = 25°C, I _D = 0.5A, V _{DD} = 24V	E _{AS}	90	mJ
Electrostatic discharge (Human body model)	V _{ESD}	4000	V
Charged device model	V _{CDM}	1000	
Thermal Resistance.Junction- to-Ambient ^(a)	R _{thJA}	150	
Thermal Resistance.Junction- to-Ambient ^(b)	R _{thJA}	83	°C/W
Thermal Resistance.Junction- to-Case ^(c)	R _{thJC}	44	
Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{stg}	-55 to 150	

Note:

(a) For a device surface mounted on a 15mm x 15mm single sided 1oz weight copper on 1.6mm FR4 board,in still air conditions.

(b) For a device surface mounted on 50mm x 50mm single sided 2oz weight copper on 1.6mm FR4 board,in still air conditions.

(c) Thermal resistance from junction to the mounting surface of the drain pin.

**N-Channel Self Protected
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ZXMS6004FF(KXMS6004FF)**

■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Test Conditions		Min	Typ	Max	Unit
Static Characteristics							
Drain-Source Clamp Voltage	$V_{DS(AZ)}$	$I_D=10 \text{ mA}$, $V_{GS}=0\text{V}$		60		70	V
Off-state drain Current	I_{DSS}	$V_{DS}=12\text{V}$, $V_{IN}=0\text{V}$				500	nA
		$V_{DS}=36\text{V}$, $V_{IN}=0\text{V}$				1	μA
Input threshold voltage	$V_{IN(\text{th})}$	$V_{DS}=V_{GS}$, $I_D=1\text{mA}$		0.7		1.5	V
Input Current	I_{IN}	$V_{IN}=+3\text{V}$				100	μA
Input Current	I_{IN}	$V_{IN}=+5\text{V}$				200	
Input current while over temperature active		$V_{IN}=+5\text{V}$				220	
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{IN}=+3\text{V}$, $I_D=0.5\text{A}$				600	$\text{m}\Omega$
		$V_{IN}=+5\text{V}$, $I_D=0.5\text{A}$				500	
Continuous drain current ^(a)	I_D	$V_{IN}=3\text{V}$, $T_A=25^\circ\text{C}$		0.9			A
Continuous drain current ^(a)	I_D	$V_{IN}=5\text{V}$, $T_A=25^\circ\text{C}$		1			A
Continuous drain current ^(b)	I_D	$V_{IN}=3\text{V}$, $T_A=25^\circ\text{C}$		1.2			A
Continuous drain current ^(b)	I_D	$V_{IN}=5\text{V}$, $T_A=25^\circ\text{C}$		1.3			A
Current limit	$I_{D(LIM)}$	$V_{IN}=+3\text{V}$		0.7			A
Current limit ^(d)	$I_{D(LIM)}$	$V_{IN}=+5\text{V}$		1			A
Dynamic characteristics							
Turn-On DelayTime	$t_{d(on)}$	$V_{GS}=5\text{V}$, $V_{DS}=12\text{V}$, $I_D=0.5\text{A}$			5		μs
Rise Time	t_r				10		
Turn-Off DelayTime	$t_{d(off)}$				45		
Fall Time	t_f				15		
Over-temperature protection							
Thermal overload trip temperature ^(e)	T_{JT}			150	175		$^\circ\text{C}$
Thermal hysteresis ^(e)					10		$^\circ\text{C}$

Notes:

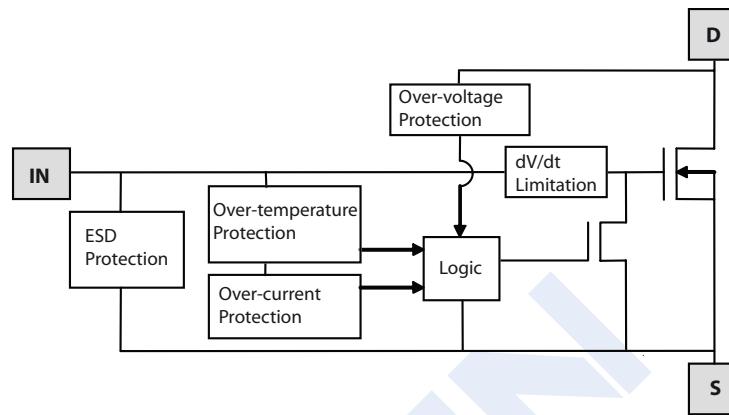
- (d) The drain current is restricted only when the device is in saturation (see graph 'typical output characteristic'). This allows the device to be used in the fully on state without interference from the current limit. The device is fully protected at all drain currents, as the low power dissipation generated outside saturation makes current limit unnecessary.
- (e) Over-temperature protection is designed to prevent device destruction under fault conditions. Fault conditions are considered as "outside" normal operating range, so this part is not designed to withstand over-temperature for extended periods.

■ Marking

Marking	1K6
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**N-Channel Self Protected
Enhancement Mode MOSFET
ZXMS6004FF(KXMS6004FF)**

■ Functional block diagram



■ Recommended operating conditions

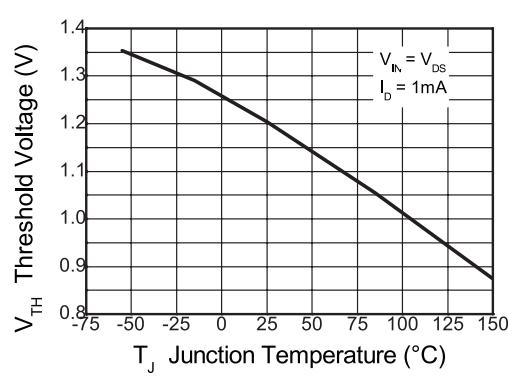
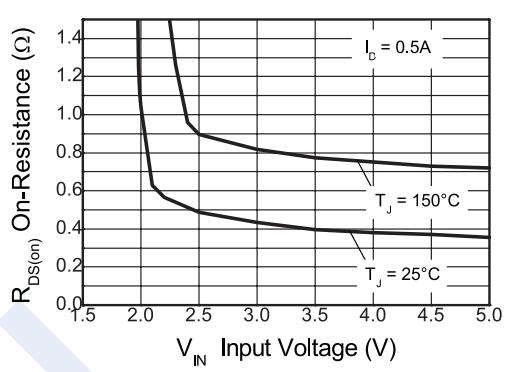
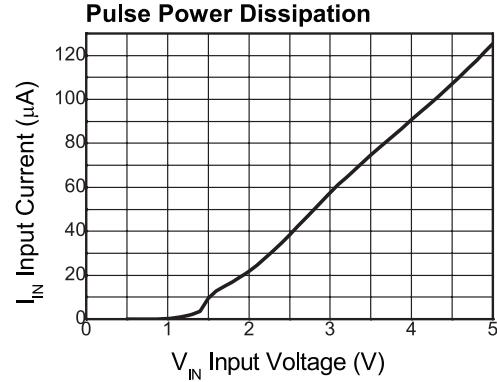
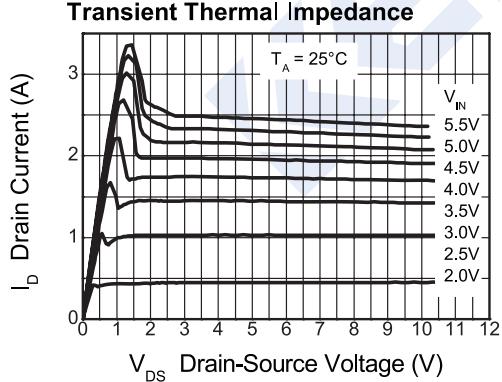
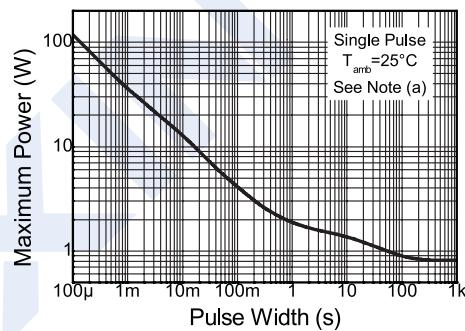
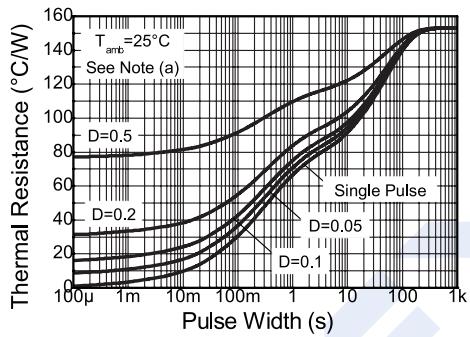
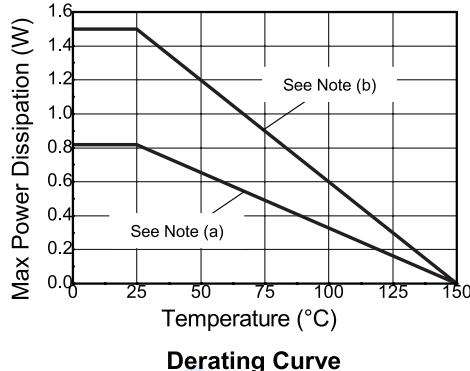
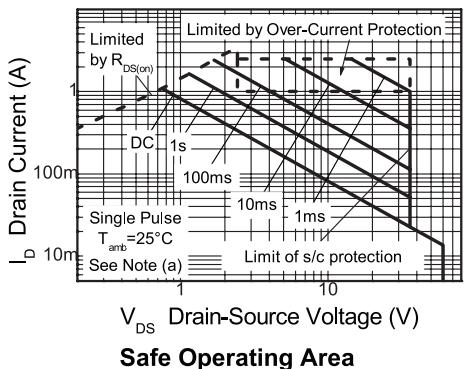
The ZXMS6004FF is optimised for use with µC operating from 3.3V and 5V supplies.

Symbol	Description	Min	Max	Units
V_{IN}	Input voltage range	0	5.5	V
T_A	Ambient temperature range	-40	125	°C
V_{IH}	High level input voltage for MOSFET to be on	3	5.5	V
V_{IL}	Low level input voltage for MOSFET to be off	0	0.7	V
V_P	Peripheral supply voltage (voltage to which load is referred)	0	36	V

N-Channel Self Protected Enhancement Mode MOSFET

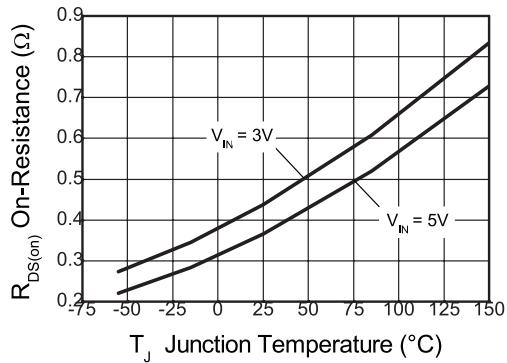
FZXMS6004FF(KXMS6004FF)

■ Typical Characteristics

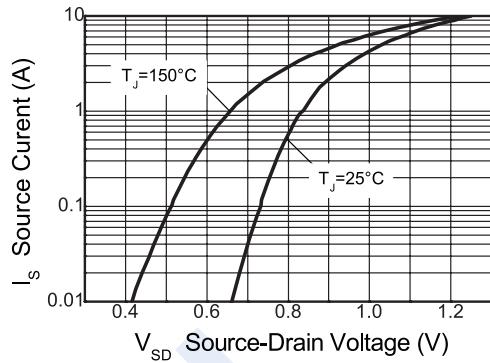


**N-Channel Self Protected
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ZXMS6004FF(KXMS6004FF)**

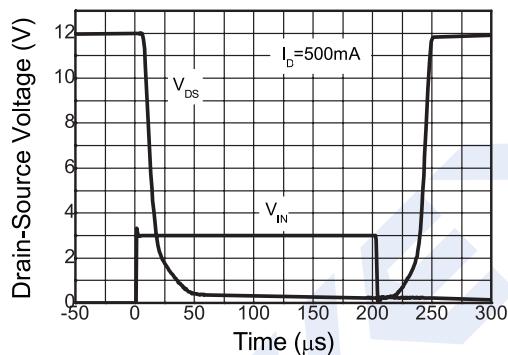
■ Typical Characteristics



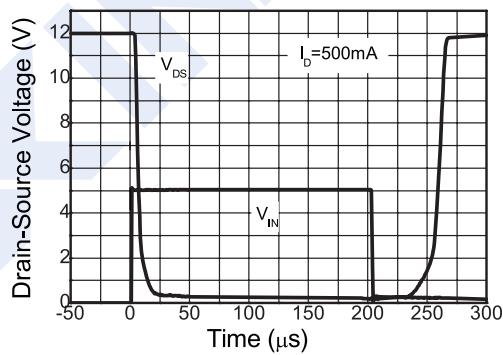
On-Resistance vs Temperature



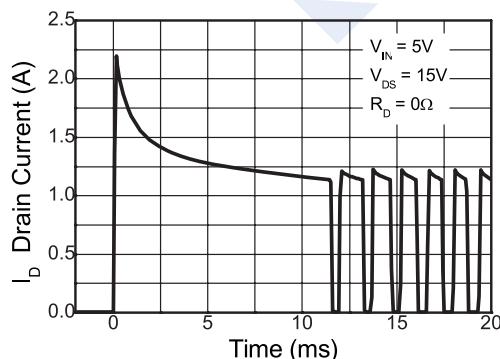
Reverse Diode Characteristic



Switching Speed



Switching Speed



Typical Short Circuit Protection